

Title (en)

Method for operating a hob and hob

Title (de)

Verfahren zum Betreiben eines Kochfelds sowie Kochfeld

Title (fr)

Procédé destiné au fonctionnement d'un champ de cuisson ainsi que champ de cuisson

Publication

EP 2600067 A1 20130605 (DE)

Application

EP 12194247 A 20121126

Priority

DE 102011087479 A 20111130

Abstract (en)

The method involves touching a touch-sensitive screen (12) for virtually displaying actual preparation vessels (7-9), and actuating a control element (10b) such that the size and/or form of the virtual preparation vessels are changed. The actual preparation vessels are positioned in respective cooking zones (3-6) on a cooking plate (2) of a cooking hob (1), where the changed size and/or form of the virtual preparation vessels are acknowledged by further touch on the touch-sensitive screen. The touch-sensitive screen is selected from one of thin film transistor (TFT) screen, an LCD screen, a plasma screen, or an organic LED screen. An independent claim is also included for a cooking hob.

Abstract (de)

Die Erfindung betrifft ein Verfahren zum Betreiben eines Kochfelds (1), wobei durch Berühren eines berührsensitiven Bildschirms (12) ein reales Zubereitungsgefäß (7, 8, 9) virtuell angezeigt wird und durch Betätigen eines Bedienelements (10b) die angezeigte Größe und/oder Form des virtuellen Zubereitungsgefäßes (13, 14, 15) verändert wird. Die Erfindung betrifft auch ein Kochfeld (1).

IPC 8 full level

F24C 7/08 (2006.01); **H05B 3/68** (2006.01)

CPC (source: EP)

F24C 7/083 (2013.01); **H05B 2213/03** (2013.01)

Citation (search report)

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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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